PRODUCT CHANGE NOTICE

PART NUMBER(S): **Please see attachment.**	**PCN No.: 06-0130-22** **DATE: January 30, 2006**

PART DESCRIPTION:

Power Management and Interface Products – Change in Wafer Fabrication Site

LEVEL OF CHANGE:

[**X**] Level I, Customer Approval.　　[ ] Level II, Customer Information.

PRODUCT ATTRIBUTE AFFECTED:

[ ] Material Change
[ ] Design Change
[**X**] Process Change
[ ] Data Sheet Change
[ ] Package Change
[ ] Packing / Shipping

[**X**] Other, Explain: Wafer Fabrication Site Transfer

DESCRIPTION OF CHANGE:

Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Silan. See attached Product List no. 22.

REASON FOR CHANGE:

Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.

FABRICATION PROCESS QUALIFICATION COMPLETED (DATE): August 7, 2006	**PRODUCT CHARACTERIZATION COMPLETED AND SAMPLES* AVAILABLE (DATE): August 23, 2006**

* Samples representative of product from the Product Family being transferred.

PRODUCT CHANGE NOTICE

EARLIEST DATE OF PRODUCTION SHIPMENTS: December 21, 2006

EFFECTIVITY CHANGE DATE OR DATE CODE: **Work week associated with earliest production shipment.**

[ ] STANDARD DISTRIBUTION **[X] CUSTOM DISTRIBUTION**

PERSON TO CONTACT WITH QUESTIONS:

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List 22

SP231ACP
SP231ACP-L
SP231ACT
SP231ACT-L
SP231AEP
SP231AEP-L
SP231AET
SP231AET-L
SP232ACNSD
SP232ACNSD-L
SP232AENSD
SP232AENSD-L
SP233ACP
SP233ACP-L
SP233ACT
SP233ACT-L
SP233AEP
SP233AEP-L
SP233AET
SP233AET-L